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TABLE OF CONTENTS

SESSION M3: ACTUATORS

CAD, DESIGN AND TEST POSTERS INTRODUCTION SESSION

MICROFABRICATION, INTEGRATION AND PACKAGING POSTERS INTRODUCTION SESSION

SESSION C4: NEW DEVICE AND COMPONENTS

SESSION M4: EMBOSSING AND MOULD

SESSION M5: CHARACTERIZATION

SPECIAL SESSION ON LARGE AREA MANUFACTURING

INVITED TALK 2: VALUE & PACKAGING

SESSION C5: MICROFABRICATION, RELIABILITY & TESTS

SESSION M6: ASSEMBLY & PACKAGING

SPECIAL SESSION CONTROL & READ-OUT ARCHITECTURES FOR MEMS AND NEMS

SESSION M7: MANUFACTURING

SESSION M8: APPLICATIONS